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Concl
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A process for the wet chemical treatment of semiconductor wafers with treatment liquids in baths, comprising the steps of

firstly treating the semiconductor wafers in a bath with an aqueous HF solution;

then treating the semiconductor wafers in a bath with an aqueous O₃ solution; and

then treating the semiconductor wafers in a bath with an aqueous HCl solution;

[wherein these treatment steps form a treatment sequence B₂ which does not need to be interrupted by rinsing with water or another treatment liquid.]

whereby these treatment steps form a treatment sequence B₂, which avoids the addition of fresh water or other liquids to the treatment baths.

REMARKS

At the outset, the Applicants wish to thank Patent Examiner Brown for the telephone interview with the undersigned attorney on January 4, 2001. During this telephone interview the above amendment to claim 1 was discussed.